



---

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16402**Generic Copy

---

**Issue Date: 03-Feb-2010****TITLE:** Add ASE-CL as Alternate Assembly Site for Selected Automotive Mixed Signal SOIC Devices**PROPOSED FIRST SHIP DATE:** 03 May 2010**AFFECTED CHANGE CATEGORY(S):** Assembly Manufacturing**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Don Warring< [don.warring@onsemi.com](mailto:don.warring@onsemi.com)>**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Sylvie Boonen<[Sylvie.Boonen@onsemi.com](mailto:Sylvie.Boonen@onsemi.com)>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.**DESCRIPTION AND PURPOSE:**

Addition of ASE-Chung Li (ASE-CL) as an alternate source assembly site for selected Automotive Mixed Signal devices in SOIC package. ASE-CL is already a qualified source of SOIC packages for other ON Semiconductor devices and is TS-16949 certified.

ASE-CL will be using its standard halogen free Bill of Materials and process flow. Package electrical, thermal, and reliability performance will be equivalent in ASE-C: to the current subcontract assembly site, Amkor Philippines. There is no impact to part form, fit, or function. ASE-CL has successfully completed reliability testing per AEC-Q100 standards at Moisture Sensitivity Level of 2 (MSL2).

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16402****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

| <b>Test</b>                | <b>Conditions</b>        | <b>Results</b> |
|----------------------------|--------------------------|----------------|
| Preconditioning            | MSL2                     | 0/552 Rejects  |
| Temperature Cycling        | -65 to +150C, 500 cycles | 0/276 Rejects  |
| Unbiased HAST              | 130C, 85%RH, 96 hours    | 0/231 Rejects  |
| Biased HAST                | 130C, 85%RH, 96 hours    | 0/231 Rejects  |
| High Temperature Storage   | 150C, 1000 hours         | 0/231 Rejects  |
| High Temperature Operation | 125C, 1000 hours         | 0/45 Rejects   |
| Solderability              | 0/45 Rejects             |                |
| Physical Dimensions        | 0/30 Rejects             |                |
| Marking Permanency         | 0/12 Rejects             |                |
| Wire Pull                  | 0/5 Rejects              |                |
| Bond Shear                 | 0/5 Rejects              |                |

**ELECTRICAL CHARACTERISTIC SUMMARY:**

There were no changes in device electrical performance or specifications. Summary data is available. Please contact your local ON Semiconductor Sales Office.

**CHANGED PART IDENTIFICATION:**

Products assembled at ASE-CL can be identified by the first character "T" of the tracecode marking.



**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16402**

**List of affected General Parts:**

**PART**

AMIS42665TJAA1G  
AMIS42665TJAA1RG  
NCV7321D10G  
NCV7321D10R2G